

High-Speed Heavy Wire Rotary Head Bonder

6600HS



F&K Delvotec's heavy wire bonder model 6600HS is the best choice for a wide range of commercially and strategically important applications in power modules, discretes and hybrids. Its outstanding robustness and the industry-leading throughput make it the most economic choice for demanding production use.

The family concept using shared hardware and software modules permits upgrades and changeovers at low cost while giving you full flexibility to follow the developments of your market. Leading-edge motion mechanics, electronics and modular software make sure that you keep your competitive advantage for many years.





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SPECIFICATIONS

Bond area	200 x 150 mm
Z-range	50 mm, 70 mm optional
Wire diameter	100 to 500 µm (4 to 20 mils)
Wire feed	Motor-driven 3" or 4" spool Quick-change snap-on wire guide Front and back-cut unit optional Integrated wire length measurement
Digital ultrasonic system	60 kHz standard; 40 kHz optional
Pattern recognition	Travelling CCD camera and Cognex
Lighting	Diffuse ring light; 1 further channel optional
Wire count	> 10,000
Die count	200 standard
Control	Pentium processor with UNIX-based operating system
Programme storage	Hard disk, floppy disk and streamer
Data transfer	Several standard options for export of quality control data
Network capability	TCP/IP network standard built in, allowing remote access for diagnosis, service and software maintenance
Quality assurance	Impedance analysis, Bond Process Control for extremely uniform bonds optional: pull tester integrated in bond head
Overall dimensions	58 x 100 x 150 cm (W x D x H) Weight approx. 550 kgrams
Line requirements	100 – 260 VAC, 50 – 60 Hz, up to 3 kW, single phase
Compressed air/vacuum	4 – 8 bar (rel.) / < -0.8 bar (rel.)

MATERIAL INPUT

Substrate size	200 x 150 mm maximum
Substrate types	Leadframes, PCBs, boats, carriers etc.
Component handling	Manual, semi-automatic, automatic, magazine to magazine or in-line

OPERATING DATA

Placement accuracy	typically better than +/- 3 µm
Cycle time/wire	450 – 650 ms, dependent on application

6600HS-001